



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)			
Parameter	Symbol	Rating	Units
Operating Temperature	T_{OPR}	-55 to +100	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to +100	$^\circ\text{C}$
Soldering Temperature (Iron) ^(2,3,4)	T_{SOL-I}	240 for 5 sec	$^\circ\text{C}$
Soldering Temperature (Flow) ^(2,3)	T_{SOL-F}	260 for 10 sec	$^\circ\text{C}$
EMITTER			
Continuous Forward Current	I_F	50	mA
Reverse Voltage	V_R	6	V
Power Dissipation ⁽¹⁾	P_D	100	mW
SENSOR			
Collector-Emitter Voltage	V_{CEO}	30	V
Emitter-Collector Voltage	V_{ECO}	4.5	V
Collector Current	I_C	20	mA
Power Dissipation ⁽¹⁾	P_D	150	mW

NOTES

1. Derate power dissipation linearly 1.67 mW/ $^\circ\text{C}$ above 25 $^\circ\text{C}$.
2. RMA flux is recommended.
3. Methanol or isopropyl alcohols are recommended as cleaning agents.
4. Soldering iron tip 1/16" (1.6mm) from housing.

ELECTRICAL/OPTICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise specified)						
PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
EMITTER						
Forward Voltage	$I_F = 20\text{ mA}$	V_F	—	1.2	1.5	V
Reverse Current	$V_R = 4\text{ V}$	I_R	—	—	10	μA
Peak Emission Wavelength	$I_F = 20\text{ mA}$	λ_{PE}	—	940	—	nm
SENSOR						
Dark Current	$V_{CE} = 10\text{ V}, I_F = 0\text{ mA}$	I_D	—	—	200	nA
	$V_{CE} = 2.5\text{ V}, I_F = 0\text{ mA}, T_A = -40^\circ\text{C to } +85^\circ\text{C}$		—	—	3	μA
COUPLED						
Collector Current	$I_F = 20\text{ mA}, V_{CE} = 10\text{ V}$	$I_{C(ON)}$	0.5	—	14	mA
Collector Emitter Saturation Voltage	$I_F = 20\text{ mA}, I_C = 0.1\text{ mA}$ $T_A = -40^\circ\text{C to } +85^\circ\text{C}$	$V_{CE(SAT)}$	—	—	0.4	V
Rise Time	$V_{CC} = 5\text{ V}, R_L = 100\ \Omega$	t_r	—	4	—	μs
Fall Time	$I_C = 5\ \mu\text{A}$	t_f	—	4	—	

TYPICAL PERFORMANCE CURVES

Fig. 1 Collector Current vs. Shield Distance

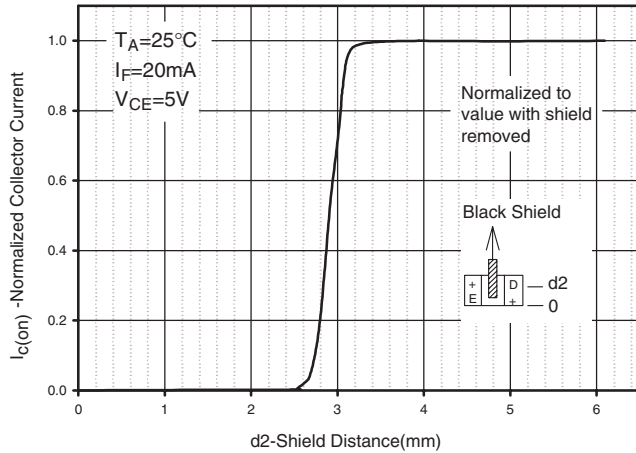


Fig. 2 Collector Current vs. Shield Distance

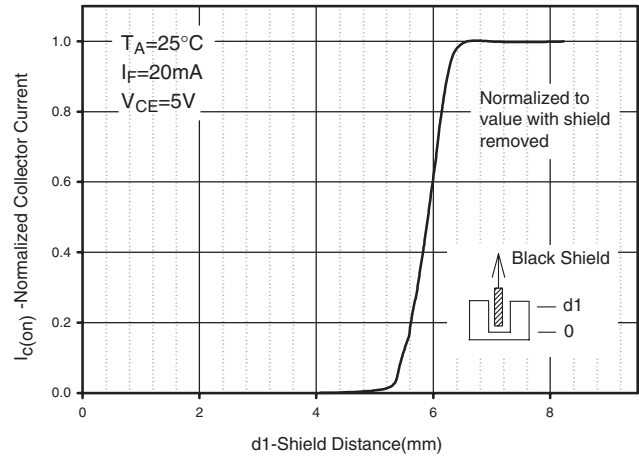


Fig. 3 Collector-Emitter Voltage vs. Collector Current

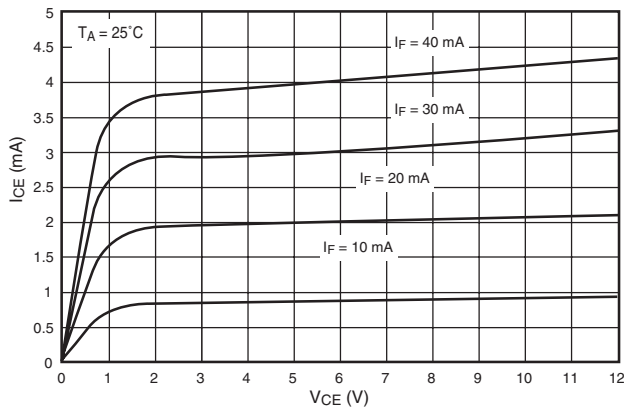


Fig. 4 Collector-Emitter Voltage vs. Temperature

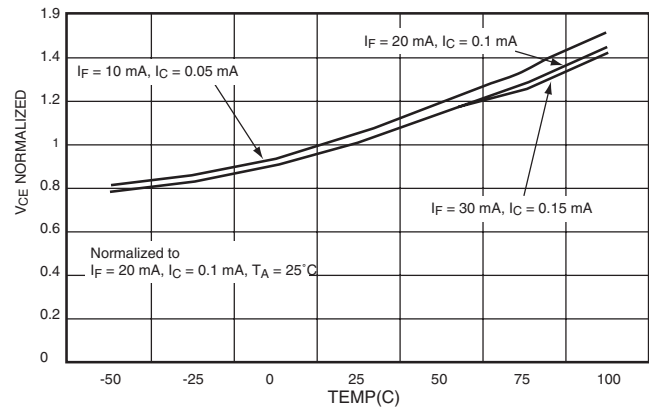


Fig. 5 Collector Current vs. Temperature

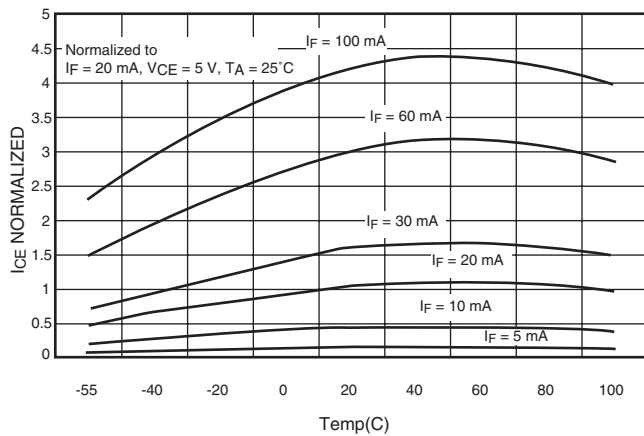


Fig. 6 Collector Current vs. Forward Current

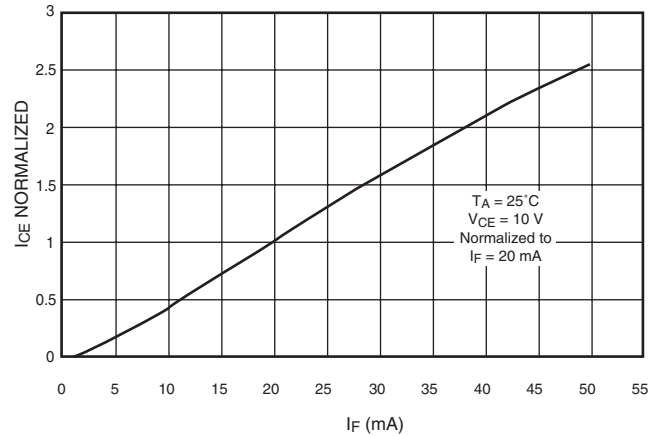


Fig. 7 Rise Time vs. Load Resistance

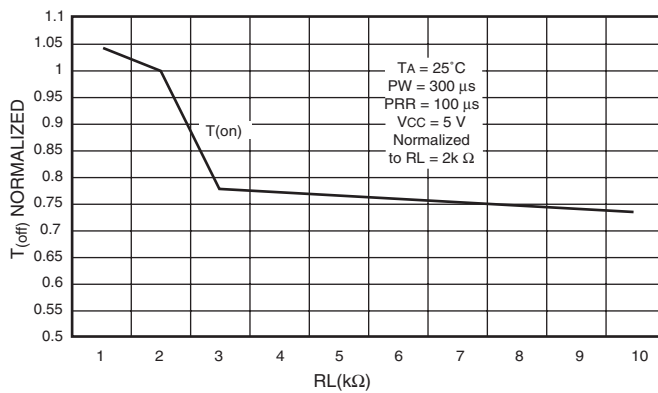


Fig. 8 Fall Time vs. Load Resistance

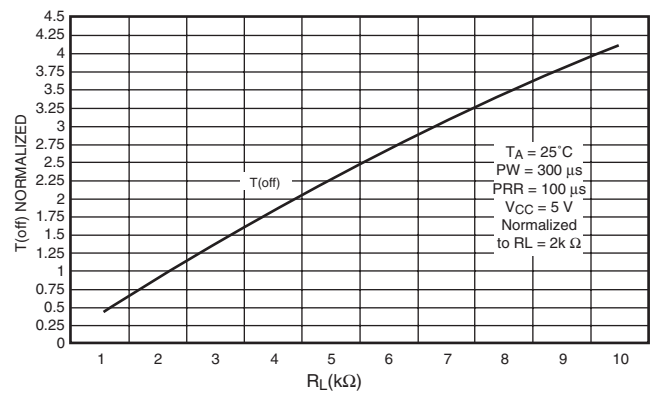
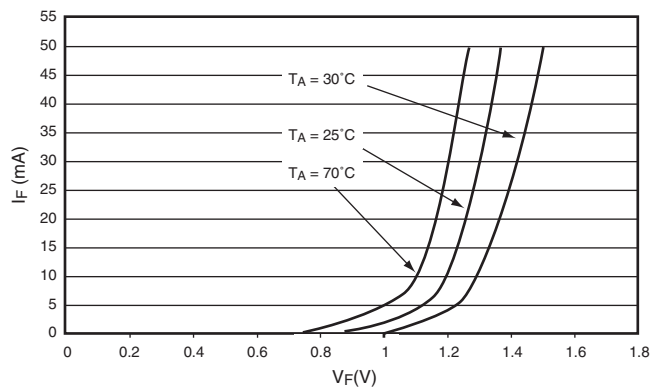


Fig. 9 Forward Voltage vs. Forward Current



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